TIL187-1 THRU TIL187-4 TIL188-1 THRU TIL188-4 AC-INPUT OPTOCOUPLERS/OPTOISOLATORS

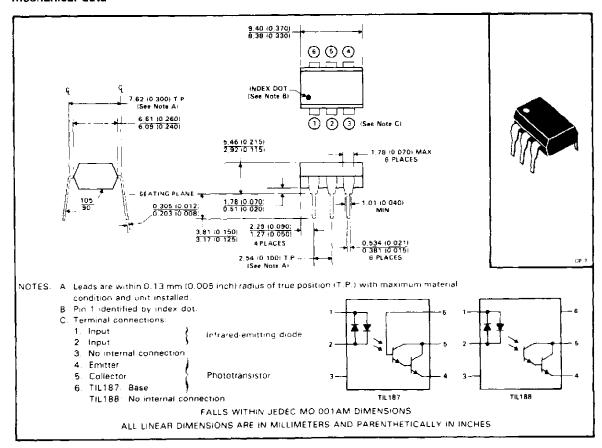
D2980. JANUARY 1987-REVISED JULY 1989 SOOS012A

- AC Signal Input
- Gallium Arsenide Dual-Diode Infrared Source Optically Coupled to a Silicon N-P-N **Darlington Phototransistor**
- Plastic Dual-In-Line Package
- High-Voltage Electrical Isolation, 3.535 kV Peak (2.5 kV rms)
- High Current Transfer Ratio, 500% Minimum at IF = 10 mA, Up to 1500% Minimum at IF = 2 mA with Four Categories
- High V(BR)CEO, 55 V Min
- UL Recognized File #E65085
- No Base Lead Connection on TIL188 for High-**FMI** Environment

description

The TIL187 and TIL188 Optocouplers are designed for use in AC applications that require very high current transfer ratio and high voltage isolation between input and output. These optocouplers consist of two GaAs light-emitting diodes connected in a reverse-parallel configuration and a silicon n-p-n Darlington phototransistor. The TIL187 has the base connected for applications where a base signal or base resistor is required. The TIL188 is designed with no base connected for applications where high base-noise immunity is desired. Users can select from four different current gains (TIL187-1 through TIL187-4 and TIL188-1 through TIL188-4).

mechanical data





TIL187-1 THRU TIL187-4 TIL188-1 THRU TIL188-4 AC-INPUT OPTOCOUPLERS/OPTOISOLATORS

absolute maximum ratings at 25 °C free-air temperature (unless otherwise noted)

Input-to-output voltage
Collector-emitter voltage (see Note 1)
Emitter-collector voltage
Emitter-base voltage (TIL187)
Input diode continuous forward current at (or below)
25 °C free-air temperature (see Note 2) 100 mA
Continuous power dissipation at (or below) 25 °C free-air temperature:
Infrared-emitting diode {see Note 3}
Phototransistor (see Note 3)
Total, infrared-emitting diode plus phototransistor (see Note 4)
Storage temperature range55 °C to 150 °C
Lead temperature 1,6 mm (1/16-inch) from case for 10 seconds

NOTES: 1 This value applies when the base-emitter diode is open circuited.

- 2. Derate linearly to 100 °C free-air temperature at the rate of 1.33 mA/°C.
- 3. Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C
- 4. Derate linearly to 100 °C free-air temperature at the rate of 3.33 mW/°C.

electrical characteristics at 25 °C free-air temperature (unless otherwise noted)

PARAMETER		TEST COMPLETIONS	TIL187 MIN TYP MAX			Til 188			144117	
		TEST CONDITIONS			MIN	TYP	MAX	UNIT		
Collector-base V(BR)CBO breakdown voltage		$I_C = 10 \mu\text{A}, \ I_E = 0,$	100							
		oltage	IF = 0				ĺ			· · ·
V.55.555	Collector-emit	tter	I _C = 1 mA, I _B = 0,	55			55			V
V(BR)CEO	breakdown vo	oltage								
Vannieno	Emitter-base		l _E = 10 μA, l _C = 0,	14						v
V(BR)EBO	breakdown ve	oltage	I _F = 0	, ,						
Vienico	Emitter-collec	i i	le = 10 μΑ, le = 0				7			V
- (BRIECO	V(BRIECO breakdown voltage		- 10 μm, η - 0							
		TIL187-1, TIL188-1		5			5			
	Photo-	TIL187-2, TIL188-2	3 IB = 0	10			10			mA
On-s	state transistor	TIL187-3, TIL188-3		20			20			
	ector operation	ITIL 187-4. TIL 188-41		30			30			
Curr	- 1		$V_{CE} = 1 \text{ V}, \text{ Ip} = 10 \text{ mA},$	50			50		1	į
	<u> </u>		(g = 0					_		
	Photodio	de operation	V _{CB} = 1 V, I _F = 10 mA,	12					μА	
			IE = 0				_			
^I C(off)	Off-state		$V_{CE} = 10 \text{ V}, I_F = 0.$			100]		100	пA
	collector curr		lB = 0							
	Transistor static		V _{CE} = 1 V, I _C = 10 mA,	25000						
hFE	forward current		lt = 0							
	transfer ratio						 			
V_F^{\dagger}	Input diode st		l⊭ = 10 m A	ו	1.2	1.5	1	1.2	1.5	V
	forward voltage		l- F0 4 1 10 4							
VCE(sat)	Collector-emitter		$I_C = 50 \text{ mA}, I_F = 10 \text{ mA},$ $I_R = 0$	0.87 1		1		0.87	1	٧
	saturation voltage Input-to-output		V _{in-quit} = ±500 V,				 		-	
rio	internal resistance		See Note 5	1011		1011		1	Ω	
	Input-to-output		$V_{\text{in-out}} = 0$, $f = 1 \text{ mHz}$,	 			 			
C_{io}	capacitance		See Note 5		1	1.3		1	1.3	p₽
IC(001)	On-state colle	ector current					 -			
<u> </u>		V _{CE} = 1 V, I _F = 2 mA	1		3	1		3		
C(on)2 symmetry ratio (see Note 6)			I			<u> </u>			L	

 $^{^{\}dagger}\text{These parameters apply for either direction of the input current.}$

NOTES: 5. These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

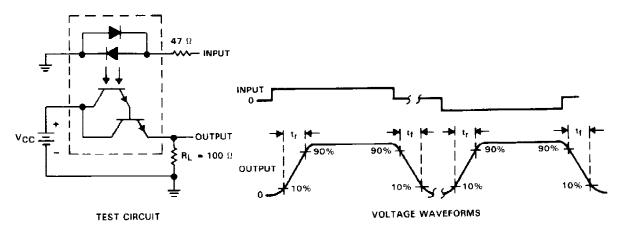
6. The higher of the two $I_{C(0n)}$ values generated by the two diodes is taken as $I_{C(0n)1}$.

switching characteristics at 25 °C free-air temperature

PARAMETER	TECT		TIL187			TIL188			
PANAMETER	1531 (CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
t, Rise time	V _{CC} = 10 V,	I _{Clont} = 10 mA,		100			100		μS
t _f Fall time	R_L - 100 Ω ,	see Figure 1		100			100		μS

PARAMETER MEASUREMENT INFORMATION

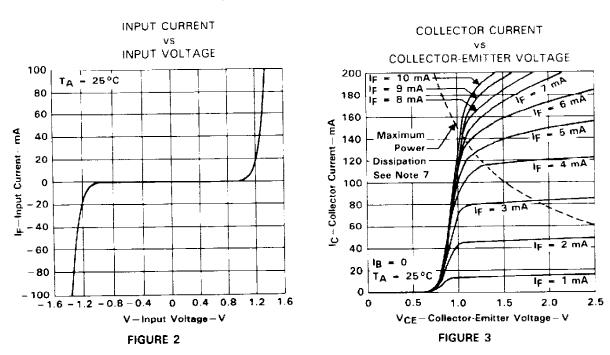
Adjust amplitude of input pulse is for IC(on) = 10 mA



NOTES: A The input waveform is supplied by a generator with the following characteristics: $|Z_0| = 50 \,\Omega$, $t_r = \pm 15$ ns, duty cycle = 1%. B. The output waveform is monitored on an oscilloscope with the following characteristics: $|t_r| \le 12$ ns, $|R_1| \ge 1$ M Ω , $|C_n| \le 20$ pF.

FIGURE 1. SWITCHING TIMES

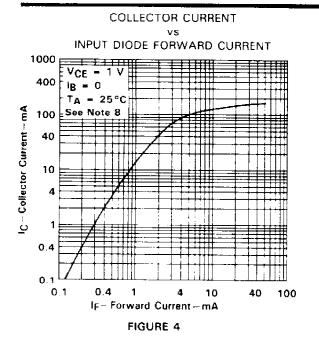
TYPICAL CHARACTERISTICS



Note 7: Pulse operation is required for operation beyond limits shown by the dashed line

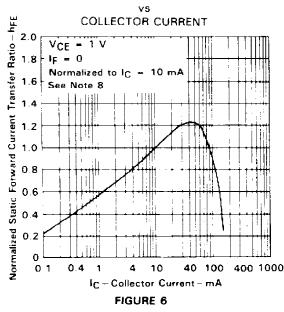


NORMALIZED ON STATE COLLECTOR CURRENT



VS FREE-AIR TEMPERATURE VCE = 1 V IF = 10 mA IB = 0 Normalized Collector Current-IC(on) 1.0 IF - 2 mA 0.8 0.6 0.4 0.2 0 -50 - 25 0 25 50 75 100 TA-Free-Air Temperature- °C

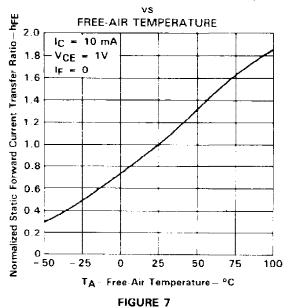
TIL187
NORMALIZED TRANSISTOR STATIC
FORWARD CURRENT TRANSFER RATIO



TIL187

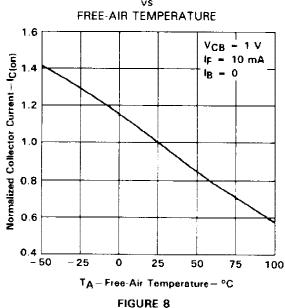
NORMALIZED TRANSISTOR STATIC
FORWARD CURRENT TRANSFER RATIO

FIGURE 5



NOTE 8: These parameters were measured using pulse techniques $t_{W} = 1$ ms, duty cycle $\leq 2\%$.

TIL187 NORMALIZED ON-STATE COLLECTOR CURRENT (PHOTODIODE OPERATION)



BREAKDOWN VOLTAGE Normalized Collector-Emitter Breakdown Voltage V(BRICEO vs FREE-AIR TEMPERATURE 1.3 Ic = 1 mA $l_B = 0$ 1.2 IF = 01.1 1.0 0.9

NORMALIZED COLLECTOR-EMITTER

FIGURE 9

TA-Free-Air Temperature- °C

50

75

OFF-STATE COLLECTOR CURRENT

0.8

0.7

- 50

- 25

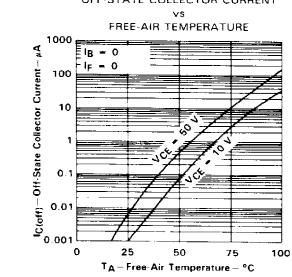


FIGURE 10

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL187-1	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL187-2	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL187-3	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL187-4	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL188-1	OBSOLETE	PDIP	Р	6	TBD	Call TI	Call TI
TIL188-2	OBSOLETE	PDIP	Р	6	TBD	Call TI	Call TI
TIL188-3	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL188-4	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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